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NOTES (UNLESS OTHERWISE SPECIFIED):

- BOARD FABRICATION METHODS MUST COMPLY WITH:
FABRICATE IN ACCORDANCE WITH IPC-6018B, per IPC-6011, CLASS 2.
- ARTWORK FORMAT: GERBER 274X
GERBER DATA SUPPLIED WITH DESIRED FINAL TRACE WIDTHS. PROCESS
COMPENSATION TRACE WIDTH ADJUSTMENTS TO BE DONE BY PCB FABRICATOR
- MATERIAL:
NUMBER OF LAYERS: 2 LAYERS
METAL 1 (TOP): 0.5oz.
CORE 1: ROGERS 4003, (0.008in.) THICK
METAL 2 (BOTTOM): 0.5oz.
SOLDERMASK TOP: LPI (LIQUID PHOTO-IMAGEABLE), GREEN.
OR LDI (LASER DIRECT IMAGEABLE), GREEN.
MAX FINISH THICKNESS OF SOLDERMASK TO BE 0.001in.
SILKSCREEN TOP: HIGH TEMPERATURE, NON-CONDUCTIVE, WHITE EPOXY BASED INK.
- FINISH PLATING:
METAL 1 (TOP) AND METAL 2 (BOTTOM):
ENIG (ELECTROLESS NICKEL/IMMERSION GOLD):
ELECTROLESS NICKEL per IPC-4552, 118 - 236µin. (3 - 6µm)
IMMERSION GOLD per IPC-4552, 3 - 10 µin (0.08 - 0.25µm)
- FINISHED BOARD THICKNESS: (0.010in.)
- COPPER IS PULLED BACK 0.002in. GROUND PLANE ONLY FROM EDGE OF BOARD ON
METAL 1 (TOP) AND METAL 2 (BOTTOM). NO PULL BACK ON TAPER.
THESE VALUES ARE CRITICAL AND MUST BE INSPECTED.
- TOLERANCE: PC BOARD OUTLINE: ±0.002in.
- BURRS SHALL NOT EXCEED 0.002in.
- VIA PLATING/FILLING:
VIAS UNDER DUT TO BE EPOXY FILLED, OVER PLATED AND PLANNERIZED.
ALL OTHER PLATED THRU HOLES TO BE PLATED TO 0.0014 ± 0.0004in. MIN. THICKNESS.
- CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.003in. OF CAD DATABASE.
- SOLDERMASK IN PLATED-THRU HOLES IS ACCEPTABLE AS LONG AS IT DOES NOT EXIST
ON BACKSIDE OF BOARD.
- ALL HOLES TO BE LOCATED WITHIN ±0.001 OF CAD DATABASE.
- NO VENDOR MARKING OR SERIALIZATION ALLOWED.
- DELIVER BOARDS BAGGED AS: SINGLES
- NO ELECTRICAL TEST NEEDED.

LAYER STACK LEGEND

Material	Layer	Thickness
	Top Paste	
	SILKSCREEN TOP	
	Surface Material	SOLDERMASK TOP 0.0004
Copper	METAL 1 TOP	0.0007
Core		0.0080
Copper	METAL 2 BOTTOM	0.0007
Total thickness: 0.010		

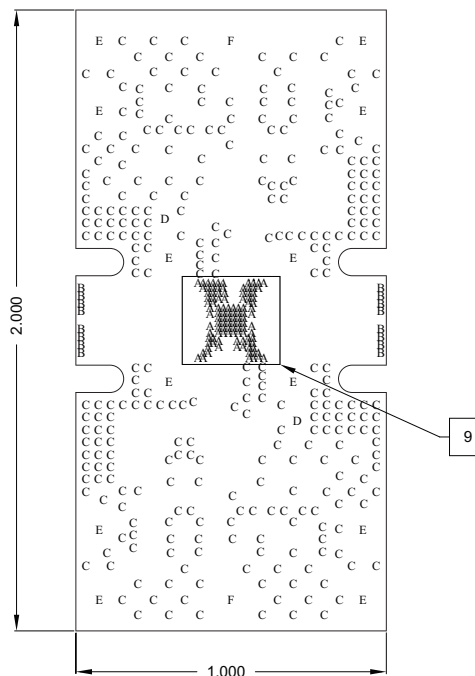
DRILL TABLE

Symbol	Count	Hole Size	Plated	Via / Pad
A	109	0.008	Plated	Via
B	16	0.015	Plated	Via
C	304	0.020	Plated	Via
D	2	0.063	Non-Plated	Pad
E	12	0.100	Plated	Pad
F	2	0.125	Plated	Pad

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REVISION HISTORY

REV	DESCRIPTION	DATE	APPROVAL
1	NEW RELEASE	03/15/17	TMONTIERTH



UNLESS OTHERWISE
SPECIFIED, DIMENSIONS
ARE IN INCHES

TOLERANCES
.XX = ±.01
.XXX = ±.005
.XXXX = ±.0010
ANGLES = ± 0.5°
INTERPRET DRAWING
PER ANSI/ASME Y14.5 - 2009

THIRD ANGLE PROJECTION
DO NOT SCALE DRAWING

SAP NO. 283907

APPROVAL AND RELEASE
RECORDS MAINTAINED IN PDE

DESIGNER	TMONTIERTH	DATE	03/15/17
ENGR.	SSCHAFFER		03/15/17

PDE CONTROLLED

CAGE
CODE 1CVM1**qorvo**TITLE:
PCB, QPL1000

SIZE	DWG. NO.	REV.
B	QPL1000-4000[1]	1
SCALE:	1:1	SHEET 1 OF 3